	Application No.	Applicant(s)	
	10/608,921	LU ET AL.	
Notice of Allowability	Examiner	Art Unit	
	Lynne A. Gurley	2812	
The MAILING DATE of this communication app All claims being allowable, PROSECUTION ON THE MERITS IS herewith (or previously mailed), a Notice of Allowance (PTOL-85 NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT F of the Office or upon petition by the applicant. See 37 CFR 1.31	S (OR REMAINS) CLOSED in 5) or other appropriate comm RIGHTS. This application is s	n this application. If not included unication will be mailed in due co	urse. THIS
1. X This communication is responsive to the application filed	<u>6/27/03</u> .		
2. ☑ The allowed claim(s) is/are <u>1-30</u> .			
3. $igotimes$ The drawings filed on <u>14 October 2003</u> are accepted by the	he Examiner.		
4. ☐ Acknowledgment is made of a claim for foreign priority to a) ☐ All b) ☐ Some* c) ☐ None of the: 1. ☐ Certified copies of the priority documents have 2. ☐ Certified copies of the priority documents have 3. ☐ Copies of the certified copies of the priority documents have also ☐ Copies of the certified copies of the priority documents have also ☐ Copies of the certified copies of the priority documents have also ☐ Copies of the certified copies of the priority documents have also ☐ Copies of the certified copies of the priority documents have also ☐ Copies ☐ Co	re been received. re been received in Applicatio ocuments have been receive " of this communication to file	on No d in this national stage application	
 THIS THREE-MONTH PERIOD IS NOT EXTENDABLE. A SUBSTITUTE OATH OR DECLARATION must be subminformal PATENT APPLICATION (PTO-152) which gives 			TICE OF
6. CORRECTED DRAWINGS (as "replacement sheets") mu (a) including changes required by the Notice of Draftsper 1) hereto or 2) to Paper No./Mail Date (b) including changes required by the attached Examiner Paper No./Mail Date Identifying indicia such as the application number (see 37 CFR each sheet. Replacement sheet(s) should be labeled as such in	rson's Patent Drawing Review - r's Amendment / Comment o 1.84(c)) should be written on to the header according to 37 CF	r in the Office action of the drawings in the front (not the ba R 1.121(d).	·
 DEPOSIT OF and/or INFORMATION about the deposit attached Examiner's comment regarding REQUIREMENT 			e the
Attachment(s) 1. ☑ Notice of References Cited (PTO-892) 2. ☑ Notice of Draftperson's Patent Drawing Review (PTO-948) 3. ☑ Information Disclosure Statements (PTO-1449 or PTO/SB/Paper No./Mail Date 10/14/03 4. ☐ Examiner's Comment Regarding Requirement for Deposit of Biological Material	6. ☐ Interview S Paper No. (08), 7. ☒ Examiner's	formal Patent Application (PTO-1 ummary (PTO-413), 'Mail Date Amendment/Comment Statement of Reasons for Allowa	ance
		LYNNE A. GURLE PRIMARY PATENT EX TC 2800, AU 2812	MINER

EXAMINER'S AMENDMENT

An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR
 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

The application has been amended as follows to clarify a typographical error (in accordance with the specification, page 7, line 22 (last line of the page)):

In claim 9, line 1, "n > 25" has been replaced by "n < 25";

In claim 19, line 1, "n > 25" has been replaced by "n < 25";

In claim 27, line 1, "n > 25" has been replaced by "n < 25".

Reasons For Allowance

- 2. The following is an examiner's statement of reasons for allowance: The prior art of record fails to teach or to suggest, either alone or in combination, the steps of the claimed invention, especially the steps of:
- 3. "exposing said semiconductor wafer to a H-S-R solution to form a S-R layer over said copper interconnects; and depositing a layer of dielectric material over said semiconductor wafer after removing said S-R layer with an in-situ plasma pretreatment of said semiconductor wafer with a hydrogen containing plasma." (claim 1)
- 4. "forming a S-R layer over said copper interconnects by polishing a copper interconnect layer with a slurry that includes H-S-R; exposing said semiconductor wafer to a H-S-R solution; and depositing a layer of dielectric material over said semiconductor wafer after removing said

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S-R layer with an in-situ plasma pretreatment of said semiconductor wafer with a hydrogen containing plasma." (claim 11)

- 5. "forming said copper interconnects by polishing a copper interconnect layer with a slurry that includes H-S-R, said polishing step also forming a S-R layer over said copper interconnects; and depositing a layer of dielectric material over said semiconductor wafer after removing said S-R layer with an in-situ plasma pretreatment of said semiconductor wafer with a hydrogen containing plasma." (claim 21)
- 6. "forming said copper interconnects by polishing a copper interconnect layer with a slurry that includes HSC₁₆H₃₃, said polishing step also forming a S-R monolayer over said copper interconnects; dipping said semiconductor wafer in a solution containing HSC₁₆H₃₃, said dipping step performed in-situ with said cleaning step; and depositing a layer of dielectric material over said semiconductor wafer after removing said S-R monolayer with an in-situ plasma pretreatment of said semiconductor wafer with a NH₃ plasma." (claim 21)
- Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Lynne A. Gurley whose telephone number is 571-272-1670. The examiner can normally be reached on M-F 7:30-4:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, John Niebling can be reached on 571-272-1679. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Lynne A. Gurley
Primary Patent Examiner

TC 2800, AU 2812

LAG June 8, 2004